HRF22

Silicon Schottky Barrier Diode for Rectifying

HITACHI

ADE-208-163D(Z)
Rev 4
Jul. 1997

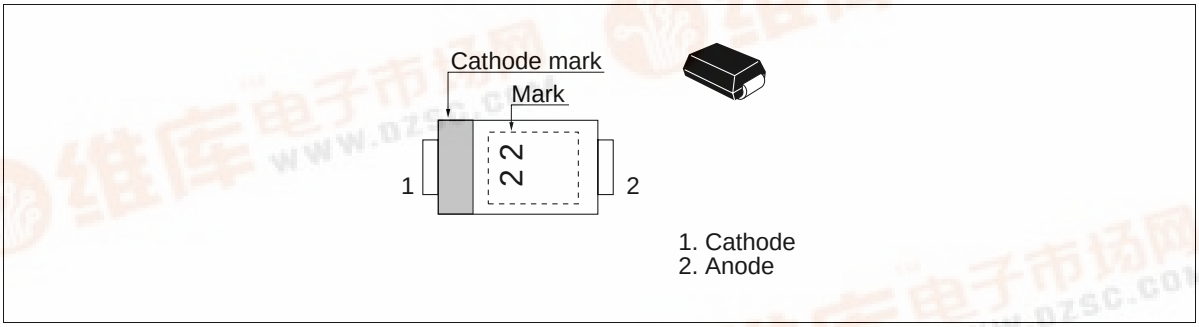
Features

- Good for high-frequency rectify.
- LRP structure ensures higher reliability.

Ordering Information

Type No.	Laser Mark	Package Code
HRF22	22	LRP

Outline



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Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM} [*1]	40	V
Average rectified current	I_o [*1]	1.0	A
Non-Repetitive peak forward surge current	I_{FSM} [*2]	20	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-40 to +125	°C

Note: 1. See from Fig.4 to Fig.7

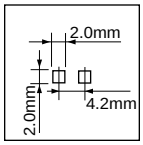
Note: 2. 10msec half sine wave 1 pulse

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	0.55	V	I_F = 1.0A
Reverse current	I_R	—	—	1.0	mA	V_R = 40V
ESD-Capability	—	150	—	—	V	C=200pF , R=0Ω, Both forward and reverse direction 1 pulse.
Thermal resistance	Rth(j-a)	—	—	108	°C/W	Alumina board [*1]
		—	—	157		Print board [*2]

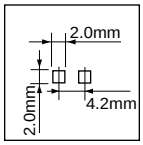
Note: 1. Alumina board

(25mm ~25mm ~0.64t



Note: 2. Print board

(25mm ~25mm ~1.64t



Main Characteristic

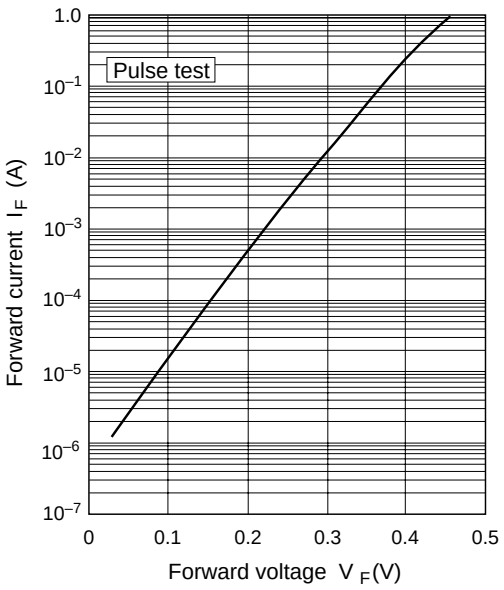


Fig.1 Forward current Vs. Forward voltage

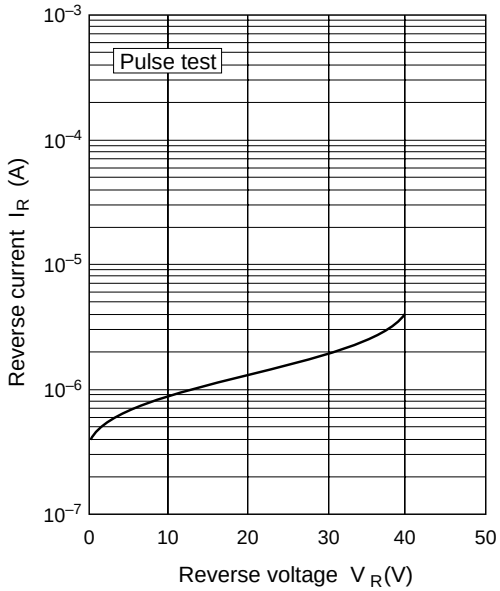


Fig.2 Reverse current Vs. Reverse voltage

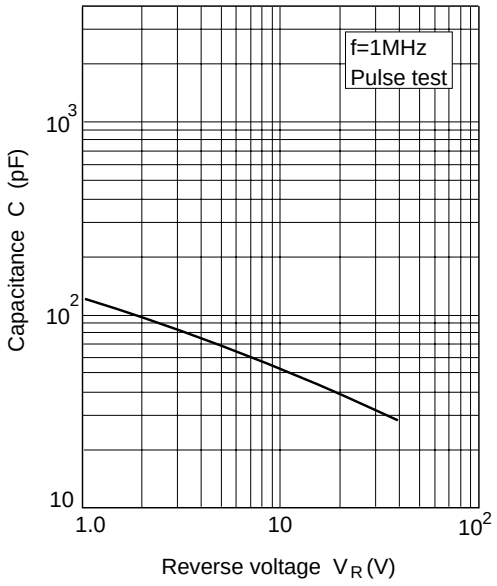


Fig.3 Capacitance Vs. Reverse voltage

Main Characteristic

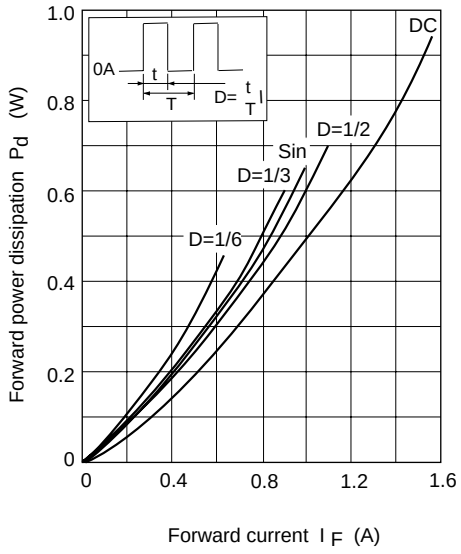


Fig.4 Forward p ower dissipation Vs. Forward current

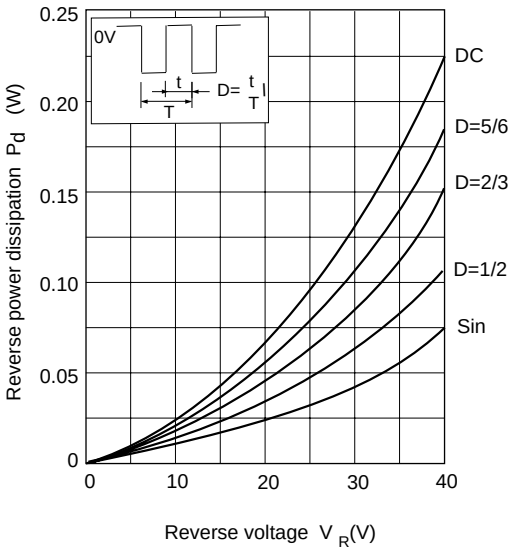


Fig.5 Reverse power dissipation Vs. Reverse voltage

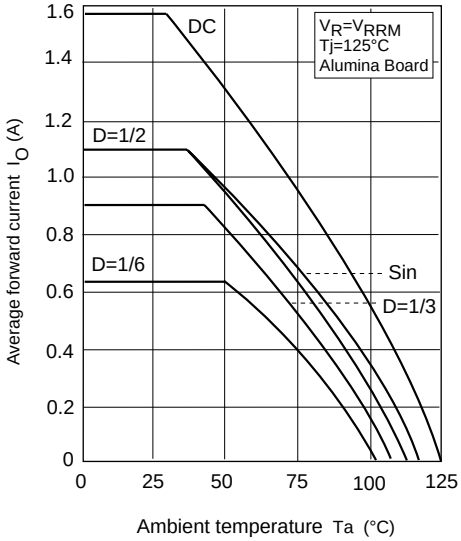


Fig.6 Average forward current Vs. Ambient temperature

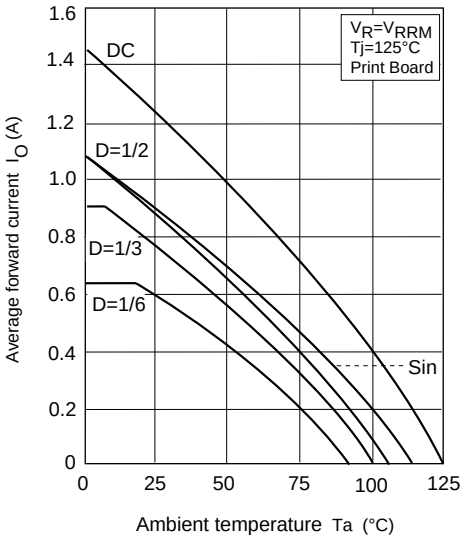
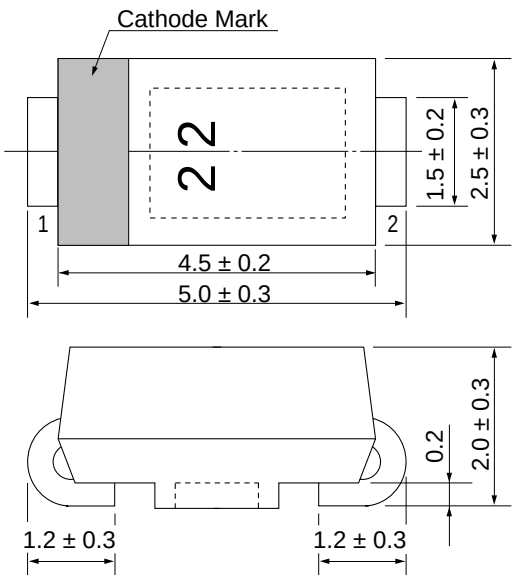


Fig.7 Average forward current Vs. Ambient temperature

Package Dimensions

Unit : mm



1 Cathode
2 Anode

Hitachi Code	LRP
JEDEC Code	—
EIAJ Code	—
Weight (g)	0.058

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HITACHI

Hitachi, Ltd.
Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose,CA 95134
Tel: <1> (408) 433-1990
Fax: <1>(408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Dornacher Straße 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building. No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX